

Product Change Notification - KSRA-20QNHD225

Date: 24 Oct 2017
Product Category: Linear Regulators
Notification subject: CCB 2846 Final Notice: Qualification of ASSH as an additional assembly site for selected products of 130K wafer technology available in 8L SOIC package using CuPdAu bond wire
Notification text: **PCN Status:**
 Final notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASSH as an additional assembly site for selected products of 130K wafer technology available in 8L SOIC package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ANAP and NSEB Assembly site

Post Change:

Assembled at ANAP, NSEB and ASSH Assembly site

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	UTAC Thai Limited (NSEB)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	UTAC Thai Limited (NSEB)	ASE-Shanghai (ASSH)
Wire material	Au Wire	Au Wire	Au Wire	Au Wire	CuPdAu Wire
Die attach material	8290	2200D	8290	2200D	EN4900G
Molding compound material	G600	G600	G600	G600	CEL-9240HF10AK
Lead frame material	C194	C194	C194	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying ASSH as an additional assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
November 24, 2017(date code: 1747)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2017					-->	October 2017				November 2017			
	13	14	15	16	17		40	41	42	43	44	45	46	47
Workweek														
Initial PCN Issue Date		X												
Qual Report Availability									X					
Final PCN Issue Date									X					
Estimated Implementation Date													X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
April 05, 2017: Issued initial notification.
October 24, 2017: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on November 24, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_KSRA-20QNHD225_Affected CPN.pdf](#)
 - [PCN_KSRA-20QNHD225_Qual Report.pdf](#)
 - [PCN_KSRA-20QNHD225_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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KSRA-20QNHD225 -CCB 2846: Initial Notice: Qualification of ASSH as an additional assembly site for selected products of 130K wafer technology available in 8L SOIC package using CuPdAu bond wire

Affected Catalog Part Number (CPN)

PCN_KSRA-20QNHD225
CATALOG_PART_NBR
MCP1726-0802E/SN
MCP1726-1202E/SN
MCP1726-1802E/SN
MCP1726-2502E/SN
MCP1726-3002E/SN
MCP1726-3302E/SN
MCP1726-5002E/SN
MCP1726-ADJE/SN
MCP1726T-0802E/SN
MCP1726T-1202E/SN
MCP1726T-1802E/SN
MCP1726T-2502E/SN
MCP1726T-3002E/SN
MCP1726T-3302E/SN
MCP1726T-5002E/SN
MCP1726T-ADJE/SN
TC1107-2.5VOA
TC1107-2.5VOATR
TC1107-2.7VOA
TC1107-2.7VOATR
TC1107-2.8VOA
TC1107-2.8VOATR
TC1107-3.0VOA
TC1107-3.0VOATR
TC1107-3.3VOA
TC1107-3.3VOATR
TC1107-5.0VOA
TC1107-5.0VOATR
TC1173-2.5VOA
TC1173-2.5VOATR
TC1173-2.7VOA
TC1173-2.7VOATR
TC1173-2.8VOA
TC1173-2.8VOATR
TC1173-3.0VOA
TC1173-3.0VOATR
TC1173-3.3VOA
TC1173-3.3VOATR
TC1173-5.0VOA
TC1173-5.0VOATR
TC1174VOA
TC1174VOATR
TC1263-2.5VOA

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Affected Catalog Part Number (CPN)

PCN_KSRA-20QNHD225
CATALOG_PART_NBR
TC1263-2.5VOATR
TC1263-2.8VOA
TC1263-2.8VOATR
TC1263-3.0VOA
TC1263-3.0VOATR
TC1263-3.3VOA
TC1263-3.3VOATR
TC1263-4.5VOATR
TC1263-5.0VOA
TC1263-5.0VOATR
TC1265-1.8VOA
TC1265-1.8VOATR
TC1265-2.5VOA
TC1265-2.5VOATR
TC1265-3.0VOA
TC1265-3.0VOATR
TC1265-3.3VOA
TC1265-3.3VOATR